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# Investigation of the diffusion behaviour of aluminium in different semiconductors

by

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**Supervisor: Professor E. Friedland**



# SUMMARY

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In the semiconductor technology aluminium is used for the production of contacts as well as a dopant. When such a semiconductor-aluminium compound in an electronic circuit is exposed to heat or radioactivity its physical properties can alter due to thermal and radiation enhanced diffusion. It is important to know the diffusion behaviour of these compounds to predict lifetimes of circuits. However, reported diffusion coefficients of aluminium in several previously investigated semiconductors are contradictory. It is important to understand the reasons for these discrepancies and additional measurements with different analysing methods have to be performed under well-controlled conditions. Furthermore diffusion data of aluminium in several compound semiconductors investigated in this study are not available.

The semiconductors investigated in this study were silicon, germanium, indium phosphide, indium antimonide and gallium arsenide. Two different methods were applied to analyse the diffusion behaviour of aluminium in these semiconductors. Firstly thin aluminium films were deposited by vapour deposition onto the investigated semiconductors. Secondly, samples were implanted at room temperature and at  $T_i = 250 \text{ }^{\circ}\text{C}$  with a fluence of  $5 \times 10^{16} \text{ aluminium ions cm}^{-2}$ .

Aluminium depth profiles for both methods were obtained by nuclear reaction analysis (NRA) before and after isochronal annealing at different temperatures. NRA is an isotope specific method that has various advantages over other analysing methods. The  $^{27}\text{Al}(\text{p},\gamma)^{28}\text{Si}$  reaction at a proton energy of 992 keV was applied to detect aluminium atoms. Diffusion coefficients as well as the detection limits of this method were extracted from a comparison of the depth profiles before and after annealing.

Additional channeling analysis in a backscattering geometry was performed to analyse the radiation-induced damage during the implantations and their recovery after isochronal annealing.

# SAMEVATTING

## Studie van die diffusiegedrag van aluminium in verskillende halfgeleiers

deur

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Voorgelê ter gedeeltelike vervulling van die vereistes vir die graad Philosophiae Doctor in die Fakulteit Natuurwetenskappe.

In die halfgeleierindustrie word aluminium vir kontakte sowel as doteermiddel gebruik. Wanneer so 'n halfgeleier-aluminium verbinding in 'n elektroniese stroombaan aan warmte of radioaktiwiteit blootgestel word, kan sy fisiese eienskappe as gevolg van termies- en stralings-versnelde diffusie verander. Dit is belangrik om die diffusie-gedrag van hierdie verbindings te ken om die leeftye van stroombane te voorspel. In die literatuur is uiteenlopende diffusiekoëfisiënte vir aluminium in 'n aantal halfgeleiers gepubliseer. Dit is belangrik om die redes hiervoor te verstaan en verdere metings met verskillende tegnieke onder beheerde omstandighede is derhalwe nodig. Verder is diffusie-data van aluminium in verskeie saamgestelde halfgeleiers wat in hierdie studie ondersoek is, nie beskikbaar nie.

Die halfgeleiers wat in hierdie studie ondersoek is, is silikon, germanium, indiumfosfied, indiumantimonied en galliumarsenied. Twee verskillende tegnieke is gebruik om die diffusiegedrag van aluminium in hierdie halfgeleiers te ondersoek. Eerstens is dun aluminiumlagies op die halfgeleiers opgedamp. Tweedens is die halfgeleier by kamertemperatuur en 250 °C met 'n dosis van  $5 \times 10^{16}$  aluminiumione  $\text{cm}^{-2}$  geïnplanteer.

Aluminiumdiepteprofile is vir albei metodes deur middel van kernreaksieanaliese (NRA) voor en na isochroniese uitgloeiing by verskillende temperature bepaal. NRA is 'n isotoopspesifieke tegniek met verskeie voordele bo ander tegnieke. Die  $^{27}\text{Al}(\text{p},\gamma)^{28}\text{Si}$ -reaksie by 'n protonenergie van 992 keV is gebruik om aluminiumatome waar te neem. Diffusiekoeffisiënte sowel as die gevoeligheid van hierdie tegniek is verkry deur die diepteprofiele voor en na uitgloeiing te vergelyk.

Hierbenewens is kanaliseringsanalise in 'n terugverstrooiingsgeometrie uitgevoer om die uitgloegedrag van die stralingskade wat deur die inplantering veroorsaak is, te bepaal.

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## TABLE OF CONTENTS

<b>CHAPTER 1:</b>	<b>INTRODUCTION</b>	<b>1</b>
<b>CHAPTER 2:</b>	<b>DIFFUSION</b>	<b>3</b>
2.1. :	Diffusion coefficient	3
2.2. :	Diffusion mechanisms in solids	4
2.2.1. :	Diffusion in semiconductors	7
2.3. :	Methods for analysing diffusion coefficients	8
2.4. :	The finite difference method	10
<b>CHAPTER 3 :</b>	<b>STOPPING OF IONS IN SOLIDS</b>	<b>12</b>
3.1. :	Energy loss	12
3.1.1. :	Nuclear cross section	13
3.1.2. :	Electronic cross section	15
3.2. :	Energy loss in compounds	17
3.3. :	Energy straggling	18
3.4. :	Mean range and range straggling	20
<b>CHAPTER 4 :</b>	<b>NUCLEAR REACTION ANALYSIS (NRA)</b>	<b>22</b>
4.1. :	Nuclear reactions	23
4.2. :	Electromagnetic transitions	23
4.3. :	Depth profiling by using narrow resonances	26
4.3.1. :	Depth resolution	27
<b>CHAPTER 5 :</b>	<b>EXPERIMENTAL</b>	<b>29</b>
5.1. :	Sample preparation	29
5.1.1. :	Silicon	30

5.1.2. :	Germanium	30
5.1.3. :	Gallium arsenide	31
5.1.4. :	Indium phosphide	31
5.1.5. :	Indium antimonide	32
5.2. :	Implantations	32
5.3. :	Annealing system	33
5.4. :	The energy scanning system	33
5.5. :	$\gamma$ - Ray detection	35
5.6. :	Data acquisition	36
5.6.1. :	Setting of energy windows	38
5.6.2. :	NRA measurements	38
5.6.3. :	Magnet setting	39
5.7. :	The $^{27}\text{Al}(\text{p},\gamma)^{28}\text{Si}$ reaction	40
5.8. :	Channeling	42
5.9. :	Error calculations	44
5.10 :	Diffusion analysis	44
<b>CHAPTER 6 :</b>	<b>PREVIOUSLY PUBLISHED RESULTS</b>	<b>46</b>
6.1. :	Elemental semiconductors	46
6.1.1. :	Silicon	47
6.1.2. :	Germanium	51
6.2. :	Compound semiconductors	52
6.2.1. :	Gallium arsenide	52
6.2.2. :	Indium phosphide	56
6.2.3. :	Indium antimonide	56
<b>CHAPTER 7 :</b>	<b>RESULTS AND DISCUSSION</b>	<b>58</b>
7.1. :	Silicon	58
7.1.1. :	Aluminium diffusion into silicon	59
7.1.2. :	Room temperature implantation	60
7.1.3. :	Hot implantation	64

7.2. :	Germanium	72
7.2.1. :	Aluminium diffusion into germanium	72
7.2.2. :	Room temperature implantation	74
7.2.3. :	Hot implantation	76
7.3. :	Gallium arsenide	80
7.3.1. :	Aluminium diffusion into gallium arsenide	81
7.3.2. :	Room temperature implantation	82
7.3.3. :	Hot implantation	84
7.4. :	Indium Phosphide	89
7.4.1. :	Aluminium diffusion into indium phosphide	89
7.4.2. :	Room temperature implantation	91
7.4.3. :	Hot implantation	94
7.5. :	Indium antimonide	97
7.5.1. :	Aluminium diffusion into indium antimonide	97
7.5.2. :	Room temperature implantation	99
7.5.3. :	Hot implantation	101
<b>CHAPTER 8 :</b>	<b>SUMMARY OF RESULTS AND OUTLOOK</b>	<b>103</b>
8.1. :	Silicon	103
8.2. :	Germanium	105
8.3. :	Gallium arsenide	106
8.4. :	Indium phosphide	108
8.5. :	Indium antimonide	110
8.6. :	Outlook	112
<b>APPENDIX A</b>		<b>113</b>
<b>REFERENCES</b>		<b>114</b>